

OPTOLINQ TC-8060



Optically clear epoxy molding compound

- LED Encapsulation
- Outdoor Applications
- Low Blue Ray Decay

OPTOLINQ TC-8060 is a high-performance optical solid epoxy specifically developed for white decorative and backlight LED encapsulation. This monocomponent epoxy achieves superior adhesion performance and great transmittance. Its stability at high temperature aids towards a good package performance and long life.

OPTOLINQ TC-8060 is a low stress, heat resistant epoxy with low stress hardeners that has been designed around its warpage and moisture capabilities. Through its moisture resistant formulation it achieves superior thermal and UV resistance properties. It offers low blue-ray decay for outdoor LED applications and overall great light performance.

Cured properties

Property	Value	Unit
Specific gravity	1.3	–
Hardness	86	Shore D
Gel time	20-45	s
Spiral flow	200±50	cm
Glass transition temperature by DSC	160	°C
Coefficient of thermal expansion, α_1	75	ppm/K
Coefficient of thermal expansion, α_2	176	ppm/K
Flexural strength	110	MPa
Flexural modulus	3.1	GPa
Transmittance at 450 nm	>90	%
Refractive Index at 633 nm	1.56	-

Recommended mold parameters

Parameter	Value	Unit
Preheating temperature	40-80	°C
Molding temperature	150±10	°C
Transfer pressure	0.98-3.92	MPa

Caplinq Europe

Industrieweg 15E,
1566JN Assendelft
The Netherlands
Phone: +31 (20) 893 2224
Email: info@caplinq.com

Caplinq Corporation

80 Sirocco Crescent
Ottawa ON, K2S 2C9
Canada
Phone: +1 (613) 482-2215
Email: info@caplinq.com



Caplinq Americas

36927 Schoolcraft Rd
Livonia, MI 48150
United states of America
Phone: +1 (313) 558-8243
Email: info@caplinq.com

Caplinq Malaysia

S-08-07 Persiaran Triangle
B Lepas, Penang 11900
Malaysia
Phone: +60(12)4302223
Email: info@caplinq.com

Recommended mold parameters

Parameter	Value	Unit
Transfer time	35±15	s
Cure time	180-300	s
Post mold cure time at 150 °C	4 - 6	h

Processing Instructions

- Be sure to keep the product dry as moisture can lead to curing failures or affect the electrical integrity of compounds.
- Before use, thaw **OPTOLINQ TC-8060** for 16–24 hours at 20–25 °C with the package sealed until product reaches room temperature. Keep the packaging unopened to prevent moisture contamination.
- Products must be used up within 24 hours after thawing.

Packaging Instructions

- Keep the molding compound sealed with aluminum laminated bags, in quantity of 1 kg each bag and 10 kg each box.

Storage and Handling

To ensure the integrity of **OPTOLINQ TC-8060**, store and use the products by following the recommended conditions. Keep it away from heat sources like molding dies and lead-frame preheating panels, as prolonged heat exposure can lead to the degradation of the molding compound. Keep the product at 5°C or lower for storage and transport. Under proper conditions, the shelf life of the product is 6 months from the manufacturing date.

Please note that the provided information is based on available data and typical conditions. For specific applications and detailed test results, refer to the actual test data and conduct appropriate certifications.

Europe

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The Netherlands
Phone: +31 (20) 893 2224
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Canada

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Ottawa ON, K2S 2C9
Canada
Phone: +1 (613) 482-2215
Email: info@caplinq.com



North America

36927 Schoolcraft Rd
Livonia, MI 48150
United states
+1 (313) 558-8243
Email: info@caplinq.com

South East Asia

S-08-07 Persiaran Triangle
B Lepas, Penang 11900
Malaysia
Phone: +60(12)4302223
Email: info@caplinq.com